

☆ Green Operation compatible

## GENERAL DESCRIPTION

The MYRLP-F-RD/RE series is a synchronous step-down mini DC/DC converter which integrates an inductor and a control IC in one tiny package.

It uses an ultra-low current consumption circuit and PFM control.

The control IC and coil are integrated to achieve miniaturization, and a space-saving power supply can be configured simply by adding two external capacitors. In addition, the ultra-low current consumption circuit and PFM control method realize high efficiency with a light load.

A operating voltage range of 1.8V to 6.0V enables support for applications that require an internally fixed output voltage from 0.5V to 3.60V. It has a built-in UVLO (Under Voltage Lock Out) function, the internal P-channel

MOS driver transistor and N-channel MOS driver transistor are turned OFF when input voltage is below the UVLO detection voltage. The MYRLP-F-RD integrates CL discharge function which enables the electric charge at the

output capacitor CL to be discharged via the internal discharge switch located between the VOUT and GND.

When the devices enter stand-by mode, output voltage quickly returns to the VSS level as a result of this function.



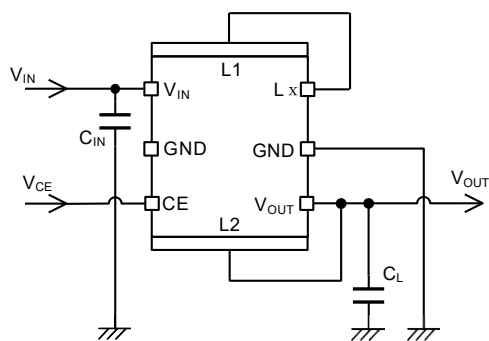
## APPLICATIONS

- Smart meter
- Low Power RF
- Sensor Module
- Wearable Devices
- Energy Harvest devices
- Back-up power supply circuit
- Smart card
- Devices with 1 Lithium cell

## FEATURES

Input Voltage Range	:	1.8V ~ 6.0V
Output Voltage Setting	:	0.5V ~ 3.60V
Output Voltage Accuracy	:	±20mV ( $V_{OUT} \leq 1.0V$ ) ±2.0% ( $V_{OUT} > 1.0V$ )
Output Current	:	150mA
Supply Current	:	200nA @ $V_{OUT}=1.8V$
Control Method	:	PFM control
Function	:	CL Discharge (MYRLP-F-RD) UVLO function
Protection Functions	:	Short Protection
Input / Output Capacitor	:	Ceramic Capacitor Compatible
Operation Ambient Temperature	:	-40 ~ 85°C
Environmentally Friendly	:	EU RoHS compliant, Pb Free Halogen Free

## TYPICAL APPLICATION CIRCUIT

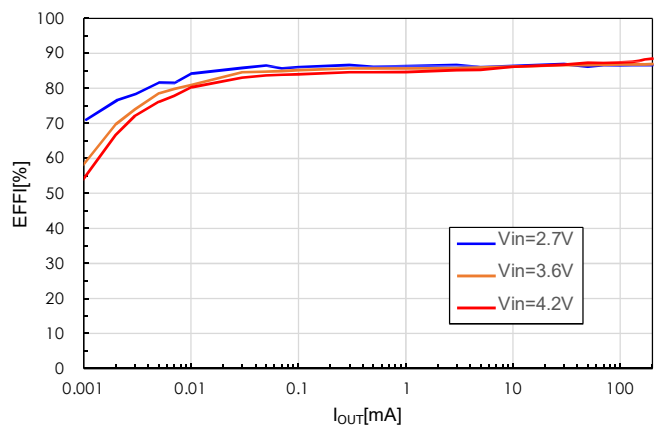


< MYRLP-F-RD/RE Series >

## TYPICAL PERFORMANCE CHARACTERISTICS

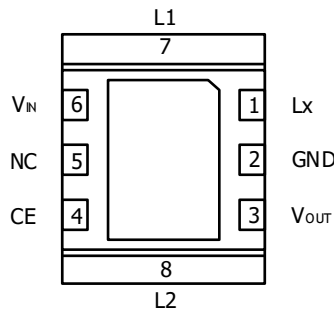
MYRLP-F-RD

$V_{OUT} = 1.8V, C_{IN} = 10\mu F, C_L = 20\mu F, T_a = 25^\circ C$





## ■ PIN CONFIGURATION



< BOTTOM VIEW >

\* The dissipation pad should be solder-plated in recommended mount pattern and metal masking to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the GND (No.2) pin.

## ■ PIN ASSIGNMENT

PIN NUMBER	PIN NAME	FUNCTION
1	Lx	Switching
2	GND	Ground
3	V <sub>OUT</sub>	Output Voltage
4	CE	Chip Enable
5	GND	Ground
6	V <sub>IN</sub>	Input Voltage
7	L1	Inductor Electrodes
8	L2	Inductor Electrodes

\* The NC (No.5) pin is not connected to the chip.

## ■ FUNCTION

PIN NAME	SIGNAL	STATUS
CE	H	Active
	L	Stand-by

\* Please do not leave the CE pin open.

## ■ PRODUCTION SUFFIX

Product Series Name	Output voltage	Output Current	Switched Type	Product Size		Package	Function
MYRLP	180	015	F	2	1	R	E/D
Ultra-Low Quiescent Current	120=1.2V 180=1.8V 330=3.3V	015=150mA	PFM Control	2=2mm *Please see tolerance	1=1mm *Please see tolerance	Tape & Reel	E= Without CL Discharge D=Wit CL Discharge

## ■ ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATINGS	UNITS
V <sub>IN</sub> Pin Voltage	V <sub>IN</sub>	-0.3 ~ 7.0	V
Lx Pin Voltage	V <sub>LX</sub>	-0.3 ~ V <sub>IN</sub> + 0.3 or 7.0 <sup>(*)</sup>	V
V <sub>OUT</sub> Pin Voltage	V <sub>OUT</sub>	-0.3 ~ V <sub>IN</sub> + 0.3 or 7.0 <sup>(*)</sup>	V
CE Pin Voltage	V <sub>CE</sub>	-0.3 ~ 7.0	V
Power Dissipation (Ta=25°C)	P <sub>d</sub>	TBD (JESD51-7board) <sup>(**)</sup>	mW
Operating Ambient Temperature	T <sub>opr</sub>	-40 ~ 85	°C
Storage Temperature	T <sub>stg</sub>	-55 ~ 125	°C

\* All voltages are described based on the GND pin.

<sup>(\*)</sup> The maximum value should be either V<sub>IN</sub>+0.3V or 7.0V in the lowest.

<sup>(\*\*)</sup> The power dissipation figure shown is PCB mounted and is for reference only.

The mounting condition is please refer to PACKAGING INFORMATION.

## ELECTRICAL CHARACTERISTICS

MYRLP-F-RD/RE Series

Ta=25°C

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNITS	CIRCUIT	
Output Voltage <sup>(*1)</sup>	V <sub>OUT</sub>	When connected to external components, I <sub>OUT</sub> = 30mA	-	<T-1>	-	V	①	
Output Voltage1-2	V <sub>OUT1-2</sub>	Voltage which Lx pin changes "H" to "L" level while V <sub>OUT</sub> is increase. <sup>(*5)</sup>	<E-1>	<E-2>	<E-3>	V	②	
Operating Voltage Range	V <sub>IN</sub>	-	<C-1>	-	6.0	V	①	
Maximum Output Current	I <sub>OUTMAX</sub>	When connected to external components <sup>(*2)</sup>	150	-	-	mA	①	
UVLO Release Voltage	V <sub>UVLOR</sub>	V <sub>OUT</sub> = 0.0V, V <sub>CE</sub> = 1.8V Voltage which Lx pin holding "H" level <sup>(*5)</sup>	Ta=25°C	-	1.50	1.78	V	②
			Ta=-40~85°C <sup>(*3)</sup>					
UVLO Detect Voltage	V <sub>UVLOD</sub>	V <sub>OUT</sub> = 0.0V, V <sub>CE</sub> = 1.8V Voltage which Lx pin holding "L" level <sup>(*5)</sup>	Ta=25°C	1.00	1.40	-	V	②
			Ta=-40~85°C <sup>(*3)</sup>					
Quiescent Current	I <sub>q</sub>	V <sub>IN</sub> = V <sub>CE</sub> = <C-1>, V <sub>OUT</sub> = V <sub>OUT</sub> × 1.05	-	<E-4>	<E-5>	nA	③	
Stand-by Current	I <sub>STB</sub>	V <sub>IN</sub> = V <sub>OUT</sub> = 6.0V	-	0.0	0.1	μA	③	
PFM Switching Current	I <sub>PFM</sub>	When connected to external components, V <sub>IN</sub> = V <sub>OUT(T)</sub> + 2.0V, I <sub>OUT</sub> = 10mA	-	400	600	mA	①	
Efficiency	EFFI	I <sub>OUT</sub> = 30mA	-	<E-6>	-	%	①	
Lx SW "H" ON Resistance	R <sub>LXH</sub>	V <sub>OUT</sub> = 0.0V, V <sub>IN</sub> = V <sub>CE</sub> = 5.0V, I <sub>LX</sub> = 50mA	-	0.35	0.45	Ω	④	
Lx SW "L" ON Resistance <sup>(*3)</sup>	R <sub>LXL</sub>	V <sub>IN</sub> = 5.0V	-	0.32	0.42	Ω	-	
Lx SW "H" Leakage Current	I <sub>LeakH</sub>	V <sub>IN</sub> = 6.0V, V <sub>OUT</sub> = V <sub>CE</sub> = 0.0V, V <sub>LX</sub> = 6.0V	-	0.0	0.1	μA	④	
Lx SW "L" Leakage Current	I <sub>LeakL</sub>	V <sub>IN</sub> = 6.0V, V <sub>OUT</sub> = V <sub>CE</sub> = 0.0V, V <sub>LX</sub> = 0.0V	-	0.0	0.1	μA	④	
Output Voltage Temperature Characteristics	$\frac{\Delta V_{OUT}}{(\Delta V_{OUT} \cdot \Delta T_{opr})}$	I <sub>OUT</sub> = 30mA -40°C ≤ T <sub>opr</sub> ≤ 85°C	-	±100	-	ppm/°C	①	
CE "H" Voltage	V <sub>CEH</sub>	V <sub>OUT</sub> = 0.0V, Voltage which Lx pin holding "H" level <sup>(*5)</sup>	Ta=25°C	1.2	-	6.0	V	②
			Ta=-40~85°C <sup>(*3)</sup>					
CE "L" Voltage	V <sub>CEL</sub>	V <sub>OUT</sub> = 0.0V, Voltage which Lx pin holding "L" level <sup>(*5)</sup>	Ta=25°C	GND	-	0.3	V	②
			Ta=-40~85°C <sup>(*3)</sup>					
CE "H" Current	I <sub>CEH</sub>	V <sub>IN</sub> = 6.0V, V <sub>OUT</sub> = 0.0V, V <sub>CE</sub> = 6.0V	-0.1	0.0	0.1	μA	⑤	
CE "L" Current	I <sub>CEL</sub>	V <sub>IN</sub> = 6.0V, V <sub>OUT</sub> = 0.0V, V <sub>CE</sub> = 0.0V	-0.1	0.0	0.1	μA	⑤	
Short Protection Threshold Voltage <sup>(*4)</sup>	V <sub>SHORT</sub>	Voltage which Lx pin holding "L" level <sup>(*5)</sup>	Ta=25°C	0.10	0.54	0.80	V	②
			Ta=-40~85°C <sup>(*3)</sup>					
CL Discharge (MYRLP-F-RD)	R <sub>DCHG</sub>	V <sub>IN</sub> = 5.0V, V <sub>CE</sub> = 0.0V, V <sub>OUT</sub> = 0.1V	29	45	60	Ω	②	
Inductance Value	L	Test Frequency=1MHz	-	2.2	-	μH		
Inductor Rated Current	I <sub>DC_L</sub>	ΔT=+40°C Current value that raises the temperature by 40°C With DC current	-	850	-	mA		

Unless otherwise stated, V<sub>IN</sub>=5V, V<sub>CE</sub>=5V, V<sub>OUT(T)</sub>=Nominal Value

(\*1) V<sub>OUT</sub> are the average values of the output voltage considering the ripple voltage and they are set so that they can be a setting output voltage with this evaluation condition.

(\*2) The maximum output current performance varies based on a voltage difference between an input voltage and an output voltage, and external components and so on. Regarding detail of this variation, please refer to OPERATIONAL EXPLANATION and NOTE ON USE section.

(\*3) Design value

(\*4) SHORT PROTECTION with LATCH is not available if V<sub>OUT1</sub> is 1.2V or less.

(\*5) "H" = V<sub>IN</sub> - 1.2V, "L" = 0.1V ~ -0.1V

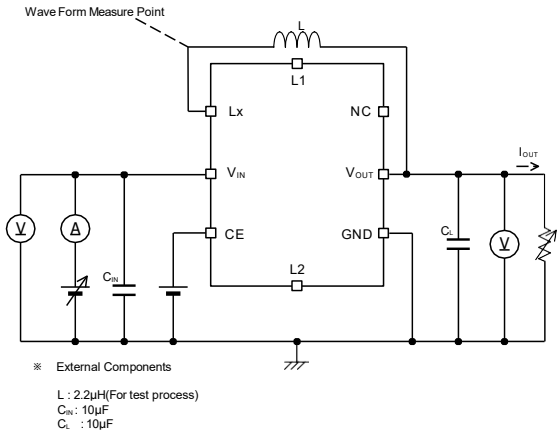
**ELECTRICAL CHARACTERISTICS**

SPEC Table

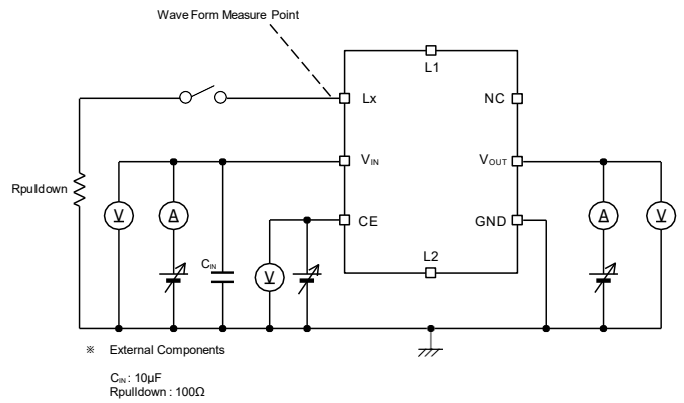
Part Number	NOMINAL OUTPUT VOLTAGE	V <sub>OUT</sub> (V)	V <sub>OUT1-2</sub> (V)			V <sub>IN</sub> (V)	I <sub>q</sub> (nA)	
		<T-1>	<E-1>	<E-2>	<E-3>	<C-1>	<E-4>	<E-5>
	V <sub>OUT(T)</sub>	TYP.	MIN.	TYP.	MAX.	V <sub>IN</sub>	TYP.	MAX.
MYRLP060015F21RD	0.60	0.600	0.560	0.580	0.600	1.80	200	600
MYRLP080015F21RD	0.80	0.800	0.760	0.780	0.800	1.80	200	600
MYRLP090015F21RD	0.90	0.900	0.860	0.880	0.900	1.80	200	600
MYRLP100015F21RD	1.00	1.000	0.960	0.980	1.000	1.80	200	600
MYRLP120015F21RD	1.20	1.200	1.156	1.180	1.204	1.80	200	600
MYRLP180015F21RD	1.80	1.800	1.744	1.780	1.816	2.30	200	600
MYRLP200015F21RD	2.00	2.000	1.940	1.980	2.020	2.50	210	630
MYRLP250015F21RD	2.50	2.500	2.430	2.480	2.530	3.00	220	660
MYRLP300015F21RD	3.00	3.000	2.920	2.980	3.040	3.50	230	690
MYRLP330015F21RD	3.30	3.300	3.214	3.280	3.346	3.80	240	720
MYRLP060015F21RE	0.60	0.600	0.560	0.580	0.600	1.80	200	600
MYRLP080015F21RE	0.80	0.800	0.760	0.780	0.800	1.80	200	600
MYRLP090015F21RE	0.90	0.900	0.860	0.880	0.900	1.80	200	600
MYRLP100015F21RE	1.00	1.000	0.960	0.980	1.000	1.80	200	600
MYRLP120015F21RE	1.20	1.200	1.156	1.180	1.204	1.80	200	600
MYRLP180015F21RE	1.80	1.800	1.744	1.780	1.816	2.30	200	600
MYRLP200015F21RE	2.00	2.000	1.940	1.980	2.020	2.50	210	630
MYRLP250015F21RE	2.50	2.500	2.430	2.480	2.530	3.00	220	660
MYRLP300015F21RE	3.00	3.000	2.920	2.980	3.040	3.50	230	690
MYRLP330015F21RE	3.30	3.300	3.214	3.280	3.346	3.80	240	720

With regard to other voltage, please contact our sales representative.

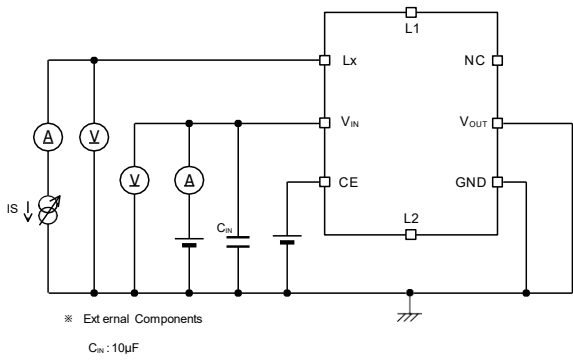
< Test Circuit No.① >



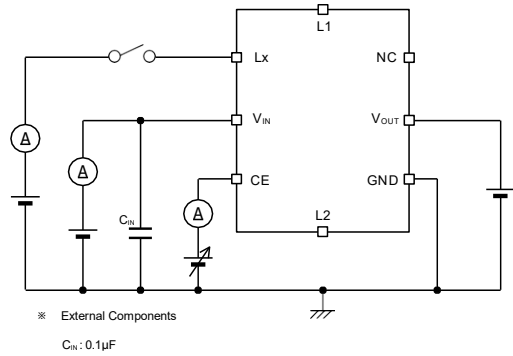
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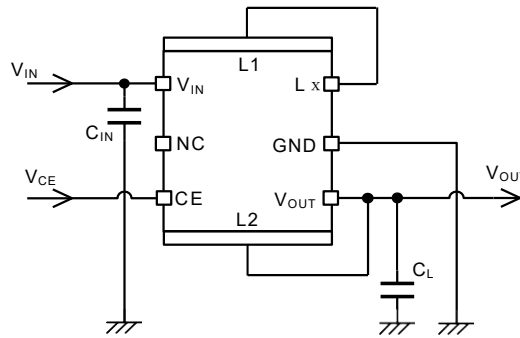
< Test Circuit No.③ >



< Test Circuit No.④ >



■ **TYPICAL APPLICATION CIRCUIT**



(NOTES):  
The coil is exclusively for this product.  
Please do not use it for any purpose other than this product.

【Typical Examples】

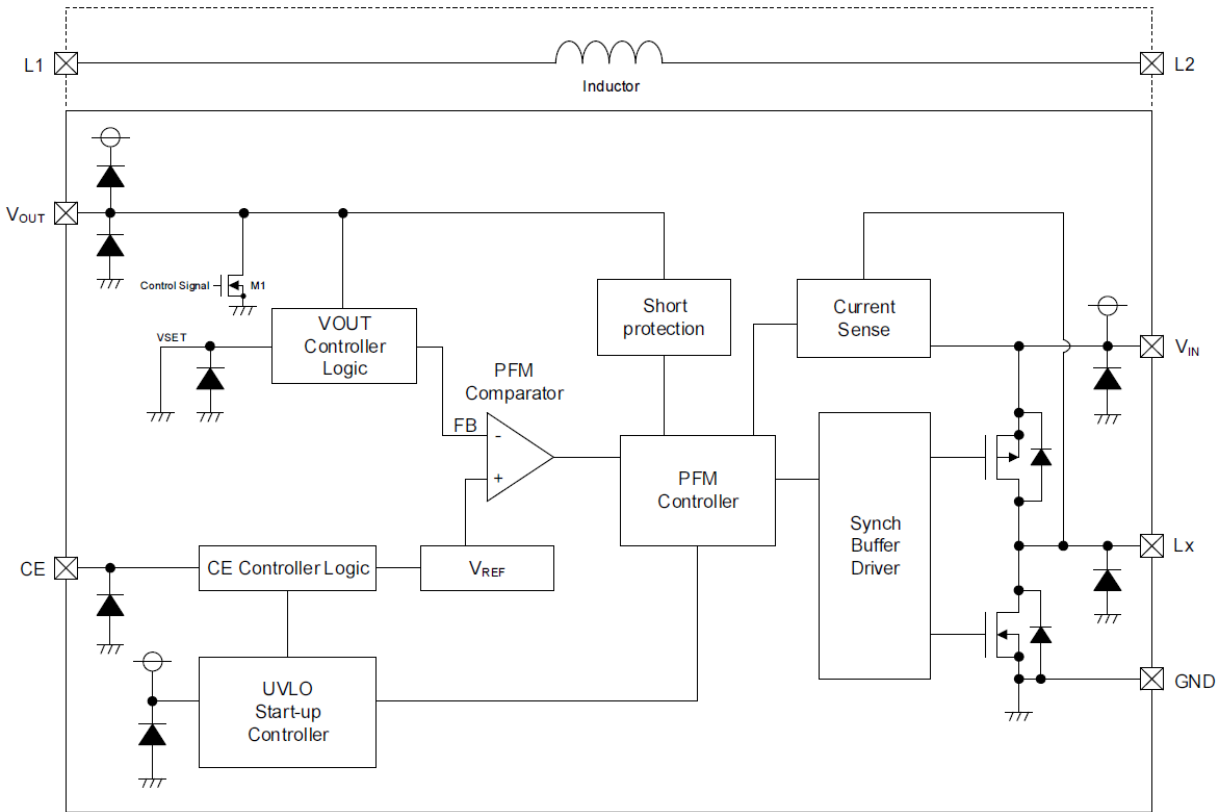
	Manufacture	Product Number	Value	Size
C <sub>IN</sub>	Murata	GRM188R61A106ME69	10μF/10V	1.6 x 0.8 x 1.0mm
C <sub>L</sub>	Murata	GRM188R61A106ME69	10μF/10V	1.6 x 0.8 x 1.0mm
		GRM188R61A226ME15	22μF/10V	

Please select the components taking into consideration the rated voltage, rated current, and ceramic capacitor DC bias characteristics, etc.  
Use a ceramic capacitor with an execution capacitance value equal to or higher than the recommended component.  
If a capacitor with a low effective capacitance value is used, the output voltage may become unstable.  
Please increase a capacitance value for C<sub>L</sub> in order to reduce output ripple voltages.  
C<sub>L</sub> such as tantalum capacitors which have a larger ESR value can increase output ripple voltages.  
If large-capacity capacitors such as electrolytic capacitors are connected in parallel, the inrush current may increase at startup and the output voltage may become unstable.



**OPERATIONAL EXPLANATION**

The MYRLP-F-RD/RE series consists of a reference voltage supply, PFM comparator, Pch driver FET, Nch driver FET, current sensing circuit, PFM control circuit, CE control circuit, and others.



< BLOCK DIAGRAM >

The efficiency performance at a light load current is significantly improved compared to existing Murata products by implementing a current limit PFM as a control method and reducing a consumption current by IC itself.

## ■ OPERATIONAL EXPLANATION (Continued)

<Normal operation>

This IC controls the output voltage by adjusting the following ①~③ operation intervals in response to the output current.

The  $V_{OUT}$  output voltage average values during actual operation depend on  $V_{OUT}$  and the ripple voltage during actual operation and are calculated as follows. For this reason, if the ripple voltage changes due to the influence of the input voltage, output voltage, or peripheral components, etc., the output voltage average value will change.

$$V_{OUT} = V_{OUT1-2} + \text{Ripple Voltage} \times 1/2$$

- ① The feedback voltage (FB voltage) is the voltage that results from dividing the output voltage with the  $V_{OUT}$  Controller logic circuit. The PFM comparator compares this FB voltage to  $V_{REF}$ . When the FB voltage is lower than  $V_{REF}$ , the PFM comparator sends a signal to the PFM control circuit to turn on the Pch driver FET.

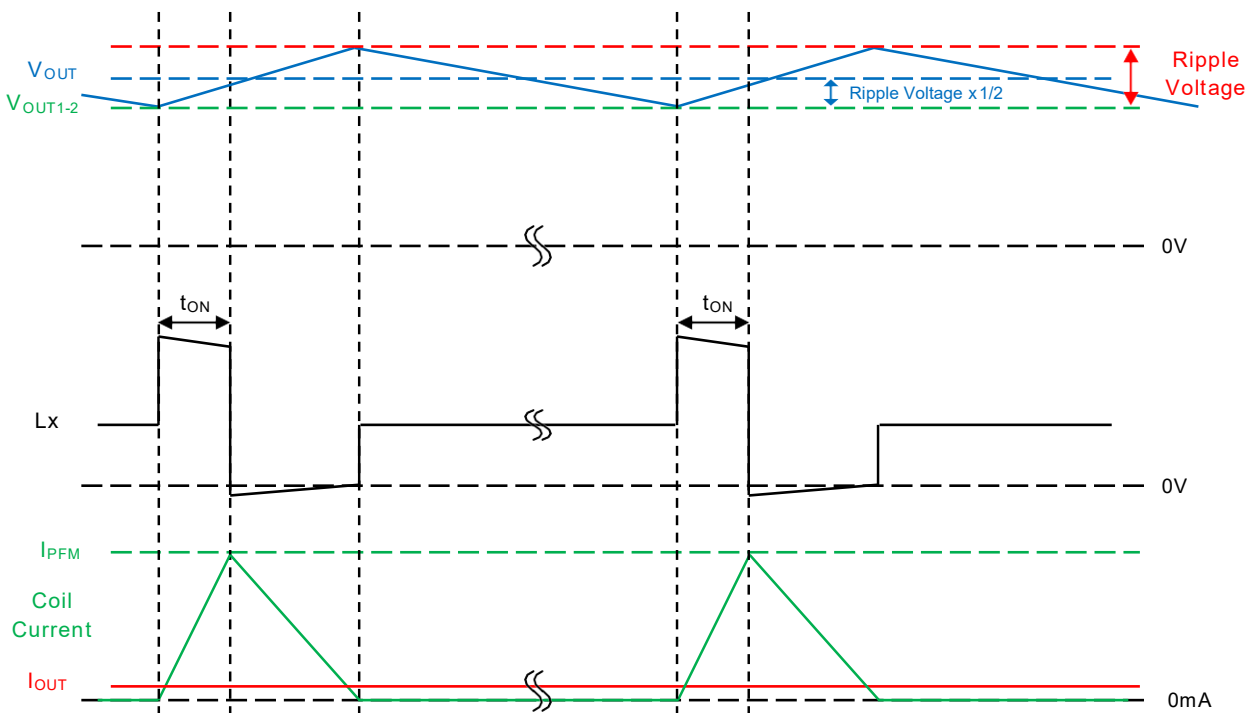
The On Time to Pch driver FET can be obtained by the following equation.

$$t_{ON} = L \times I_{PFM} / (V_{IN} - V_{OUT})$$

- ② When the Pch driver FET turns on, the coil current increases until the coil current reaches PFM Switching Current ( $I_{PFM}$ ). When the coil current reaches  $I_{PFM}$ , the Pch driver FET turns off and then the Nch driver FET turns on.

- ③ After the Nch driver FET turns on, the coil current will decrease and when the coil current goes down to approx. 0mA, the Nch driver FET will turn off. The Pch driver FET and Nch driver FET remain off until the FB voltage becomes lower than the reference voltage  $V_{REF}$ .

The above ①~③ switching operations increase the FB voltage accompanying the output voltage increase, but if the PFM comparator determines the FB voltage is lower than the reference voltage  $V_{REF}$  before the coil current reaches 0mA, the Nch driver FET turns off and the status moves to ①.



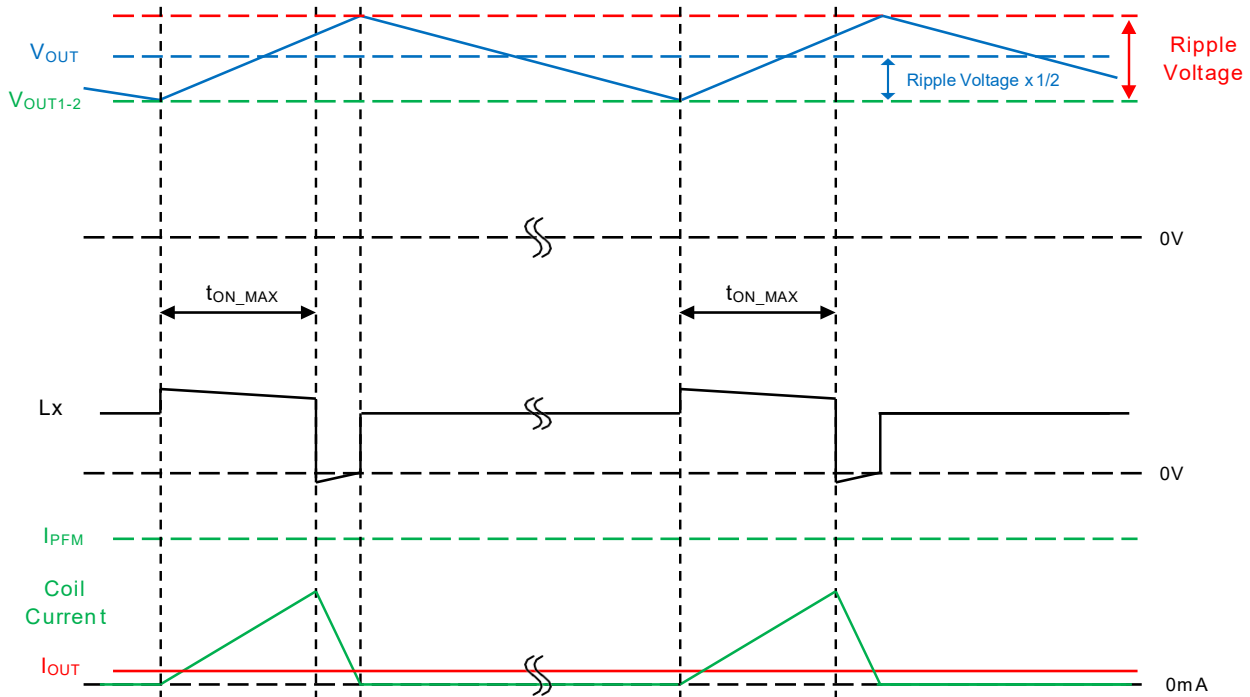
## OPERATIONAL EXPLANATION (Continued)

< Maximum on-time function, 100% Duty operation >

When the input / output potential difference decreases, the on-time required for the coil current to reach  $I_{PFM}$  increases, and the output ripple voltage tends to increase. Therefore, under conditions where the input / output potential difference is small, excessive ripple voltage is suppressed by limiting the maximum on-time that the Pch driver FET can turn on after the FB voltage becomes higher than the reference voltage  $V_{REF}$  to  $3.0\mu s$  (TYP.).

If the input / output potential difference is further reduced, the FB voltage is always lower than the reference voltage  $V_{REF}$ , so the 100% duty operation is performed and the Pch driver FET is always on.

At 100% duty, the current consumption of the IC increases compared to normal operation.



## ■ OPERATIONAL EXPLANATION (Continued)

### <CE function>

When "H" voltage ( $V_{CEH}$ ) is fed to the CE pin, normal operation starts after raising the output voltage with Start-up Mode. When the "L" voltage ( $V_{CEL}$ ) is fed to the CE pin, it enters the stand-by state and the current consumption is suppressed to  $0.0\mu\text{A}$  (TYP.). Additionally, Pch MOS driver FET and Nch MOS driver FET are turned off.

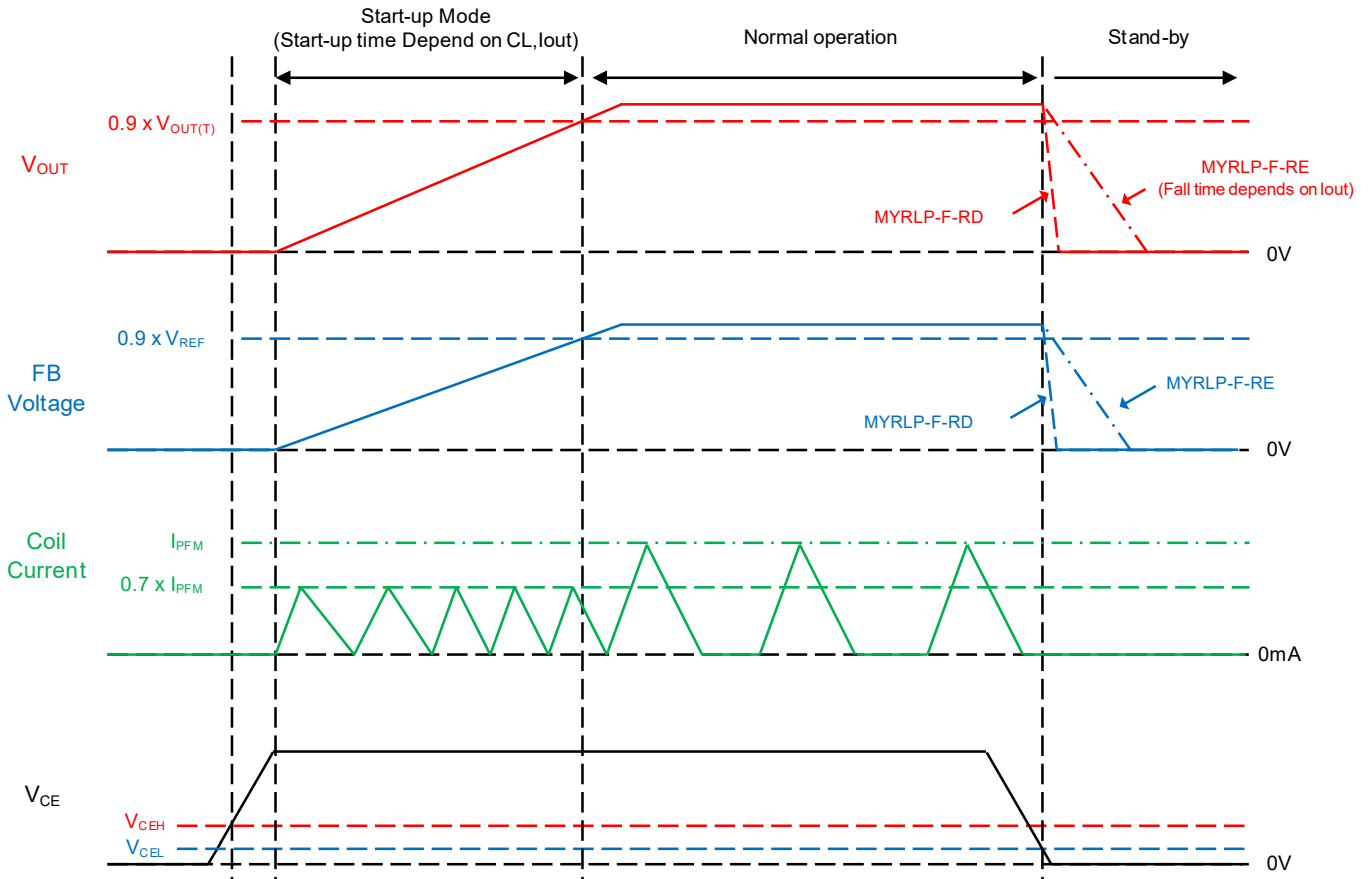
### <Start-up Mode>

After "H" voltage ( $V_{CEH}$ ) is fed to CE pin and UVLO function is released, by the time when FB voltage goes up to  $0.9 \times V_{REF}$ , the startup mode operates.

Unlike the normal operation, the start-up mode stops the operation of the short-circuit protection function and prevents the IC from being inadvertently stopped.

In order to suppress the inrush current, the peak current of the coil is limited to  $0.7 \times I_{PFM}$ , and the Nch driver FET does not turn on and the coil current flows through the parasitic diode of the Nch driver FET.

The rise time of the output voltage depends on the output capacitance and output current.



### <UVLO function>

When the  $V_{IN}$  voltage becomes UVLO Detect Voltage ( $V_{UVLOD}$ ) or less, the UVLO function operates to forcibly turn off the Pch MOS driver FET to prevent erroneous pulse output due to operation instability of the internal circuit.

During the UVLO function, the Pch driver FET and Nch driver FET turn off, and the Nch FET M1 between the  $V_{OUT}$  pin and GND pin turns on to discharge the output capacitance and make the output voltage be lower.

When the  $V_{IN}$  voltage becomes UVLO Release Voltage ( $V_{UVLOR}$ ) or more, the UVLO function is canceled. After the UVLO function is canceled, the output voltage rises with the startup mode, and then the normal operation is performed.

Moreover, during the UVLO operation, the current consumption increases because the internal circuit is operating and the switching operation is stopped, not the stand-by state.

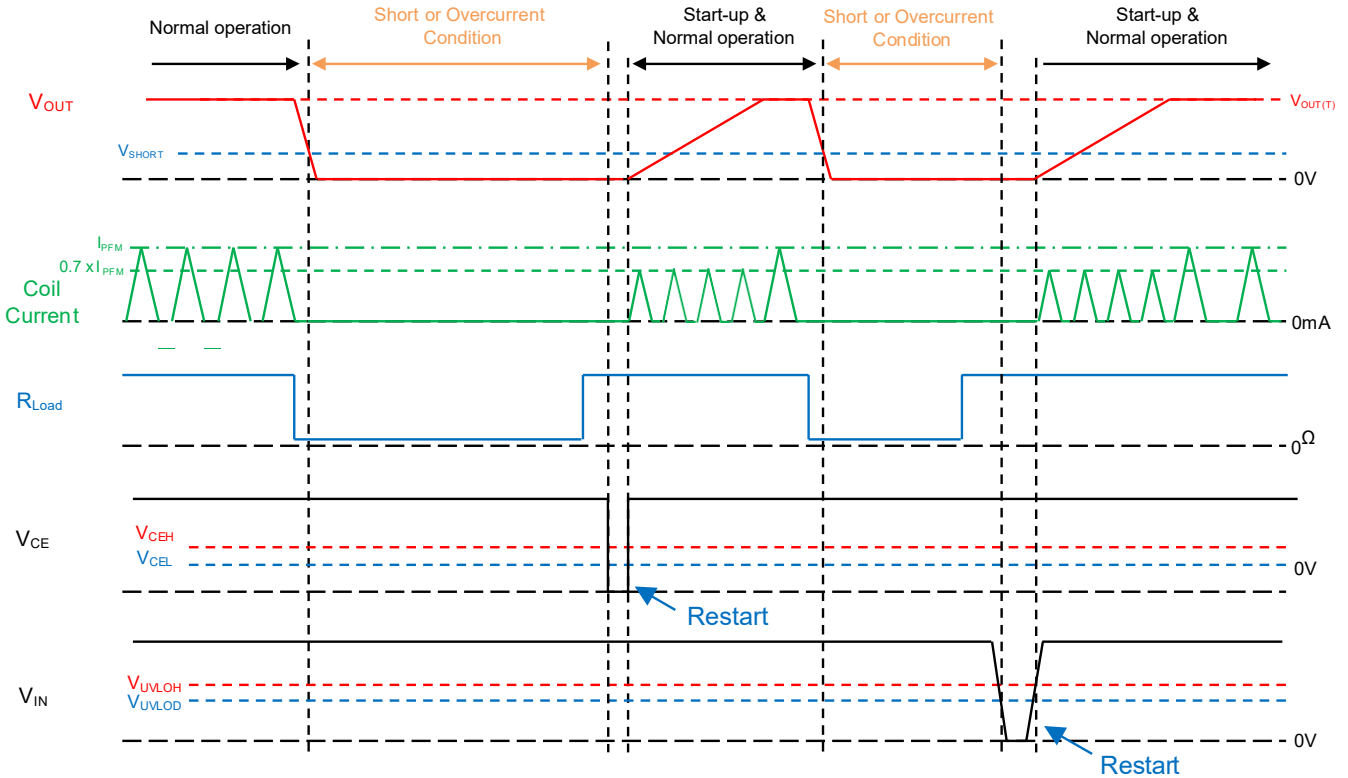
**OPERATIONAL EXPLANATION (Continued)**

•Case (a) :  $V_{OUT} \geq 1.2V$

The short-circuit protection function monitors the  $V_{OUT}$  pin voltage, and if the  $V_{OUT}$  pin voltage drops below the Short Protection Threshold Voltage ( $V_{SHORT}$ ) due to a short circuit or overcurrent, the short circuit protection function operates.

When the short-circuit protection function is activated, the Pch driver FET and Nch driver FET are held off. If the  $V_{OUT}$  pin voltage exceeds the Short Protection Threshold Voltage ( $V_{SHORT}$ ) after the short-circuit protection function is activated, normal operation resumes.

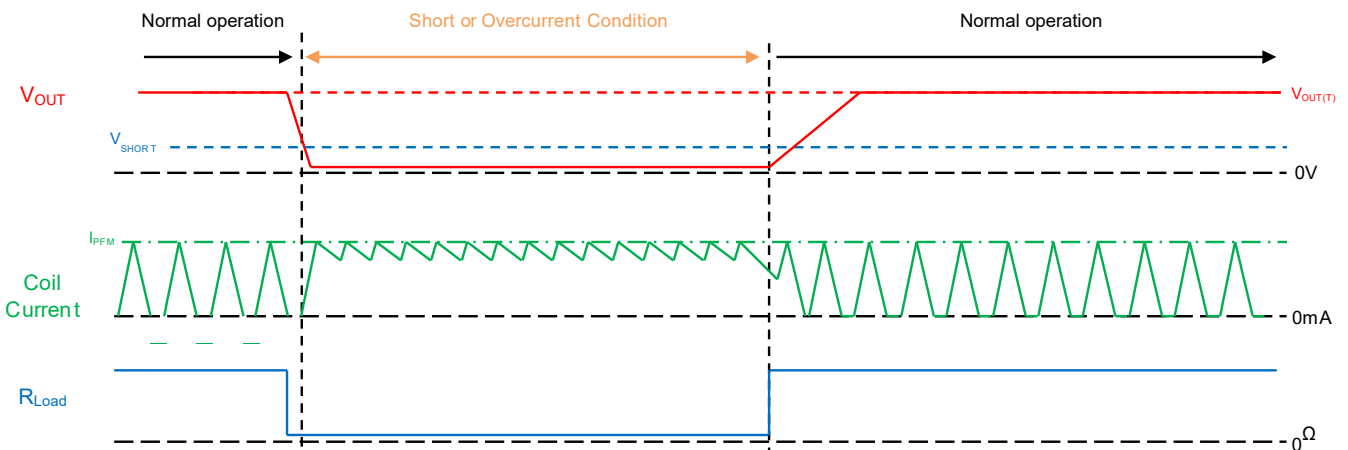
To cancel the short-circuit protection function, it is necessary to start the IC after putting the IC in the standby state with the CE function, or to raise the input voltage after setting the input voltage below the UVLO detection voltage ( $V_{UVLOD}$ ).



•Case (b) :  $V_{OUT} < 1.2V$

The short-circuit protection function is not implemented in the part numbers where  $V_{OUT}$  is less than 1.2V. If a short circuit or overcurrent occurs, the output voltage will drop and switching operation will continue.

When the short-circuit state or excessive output current is released, the output voltage rises quickly to the set output voltage.



## ■ OPERATIONAL EXPLANATION (Continued)

< CL Discharge function (MYRLP-F-RD)>

On the MYRLP-F-RD/RE series, a CL discharge function is available as an option.

CL discharge function turns on the Nch FET M1 between the VOUT pin and GND pin when the stand-by condition in order to discharge the output capacitance quickly and make the output voltage be lower.

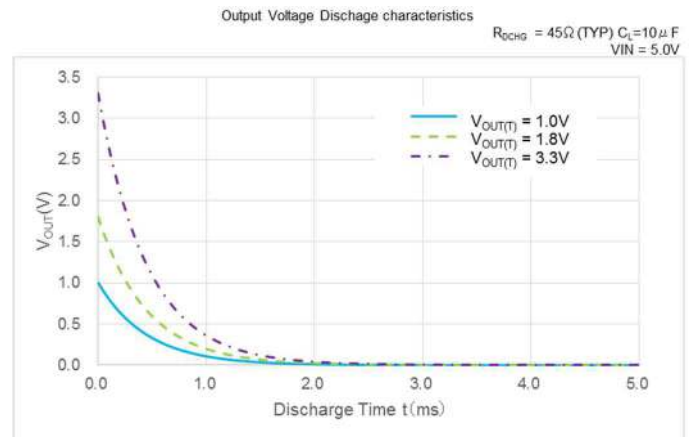
This prevents malfunctioning of the application in the event that a charge remains on CL when the IC is stand-by state.

The discharge time is determined by CL and the CL discharge resistance RDCHG, including the Nch FET M1. the discharge time of the output voltage is calculated by means of the equation below.

$$V = V_{OUT(T)} \times e^{-t/\tau}$$

$$t = \tau \ln(V_{OUT(T)} / V)$$

- V : Output voltage during discharge
- V<sub>OUT(T)</sub> : Output voltage
- t : Discharge time
- CL : Effective capacitance of Output capacitor
- RDCHG : CL auto-discharge resistance
- τ : CL × RDCHG



■ **NOTE ON USE**

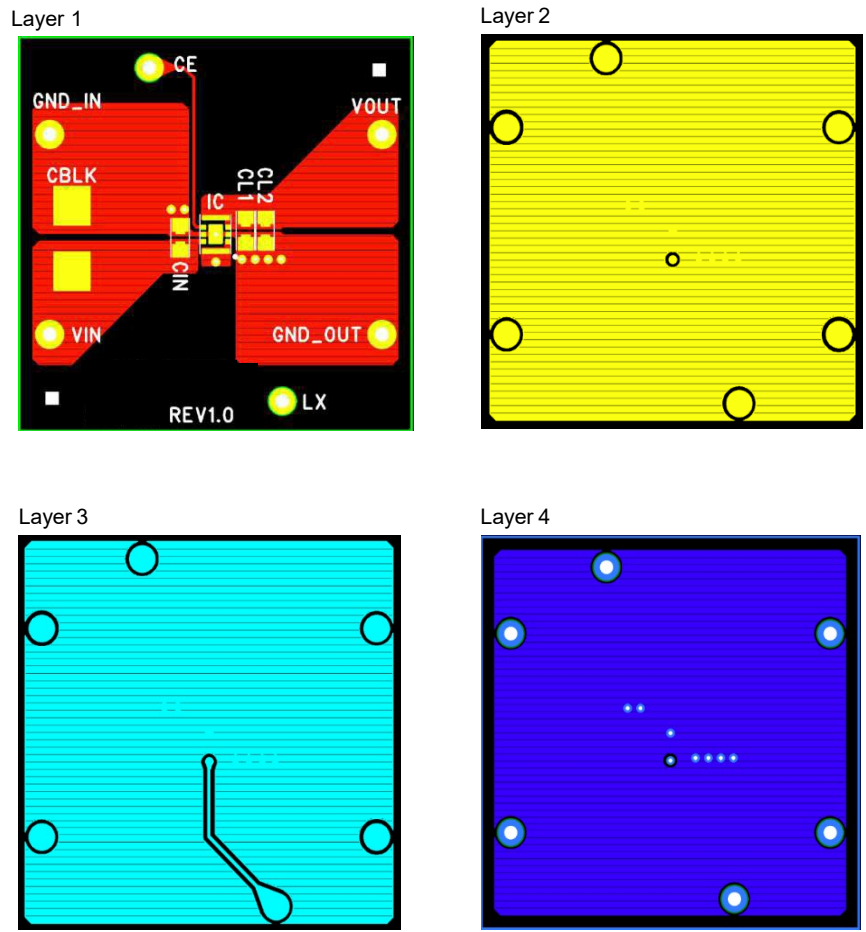
1. Be careful not to exceed the absolute maximum ratings for externally connected components and this IC.
2. The DC/DC converter characteristics greatly depend not only on the characteristics of this IC but also on those of externally connected components, so refer to EXTERNAL COMPONENTS SELECTION and the specifications of each component and be careful when selecting the components. Be especially careful of the characteristics of the capacitor used for the load capacity  $C_L$  and use a capacitor with B characteristics (JIS Standard) or an X7R/X5R (EIA Standard) ceramic capacitor.
3. The CE pin and VSET pin does not have an internal pull-up or pull-down, etc. Apply the prescribed voltage to the CE pin and VSET pin.  
If an intermediate voltage is fed to the CE and VSET pins, a through current will flow through the input stage of the CE and VSET pins, increasing current consumption.
4. At light loads or when IC operation is stopped, leakage current from the Pch driver FET may cause the output voltage to rise.
5. Switching operation may be performed continuously due to internal delay or input offset of the PFM comparator circuit.  
If the switching operation continues, the output ripple voltage increases and the output voltage rises as the ripple voltage increases.
6. When the input / output potential difference is small, the ripple voltage increases and the output voltage may increase.
7. Since the short-circuit protection function is not implemented in the part number where both of or either  $V_{OUT}$  is less than 1.2V, the coil current may be superposed under the condition of high input voltage and excessive output current.
8. During start-up mode, the peak current of the coil is set lower than in normal operation, so the output voltage may not rise under conditions where the output current is large during start-up.
9. To suppress current consumption, UVLO detection is performed only for a certain period after the Pch driver FET is turned on. For this reason, the UVLO function may not operate if the VIN pin voltage instantaneously drops below the UVLO detection voltage ( $V_{UVLOD}$ ).
10. For temporary, transitional voltage drop or voltage rising phenomenon, the IC is liable to malfunction should the ratings be exceeded.
11. Murata places an importance on improving our products and their reliability. We request that users incorporate fail-safe designs and post-aging protection treatment when using Murata products in their systems.

■NOTE ON USE (Continued)

12. Instructions of pattern layouts

- (1) In order to stabilize  $V_{IN}$  voltage level, we recommend that a by-pass capacitor ( $C_{IN}$ ) be connected as close as possible to the  $V_{IN}$  & GND pins.
- (2) Please mount each external component as close to the IC as possible.
- (3) Wire external components as close to the IC as possible and use thick, short connecting traces to reduce the circuit impedance.
- (4) Make sure that the PCB GND traces are as thick as possible, as variations in ground potential caused by high ground currents at the time of switching may result in instability of the IC.
- (5) This series' internal driver FET bring on heat because of the output current and ON resistance of Pch driver FET.

< Reference pattern layout >





## ■ Notes on handling of product

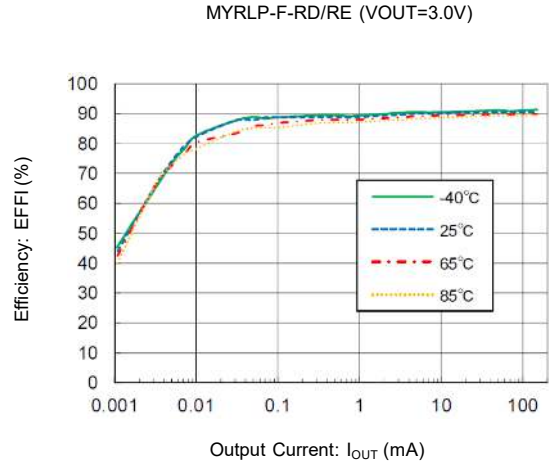
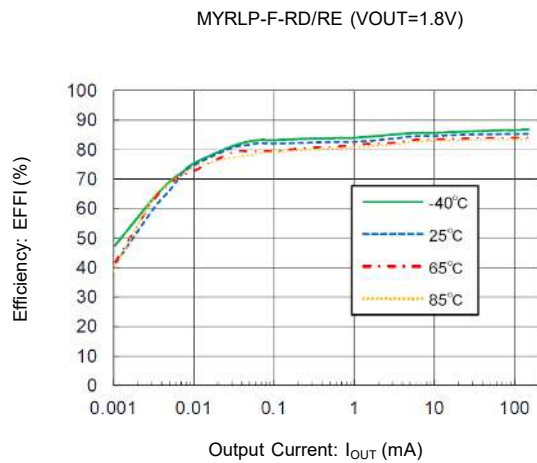
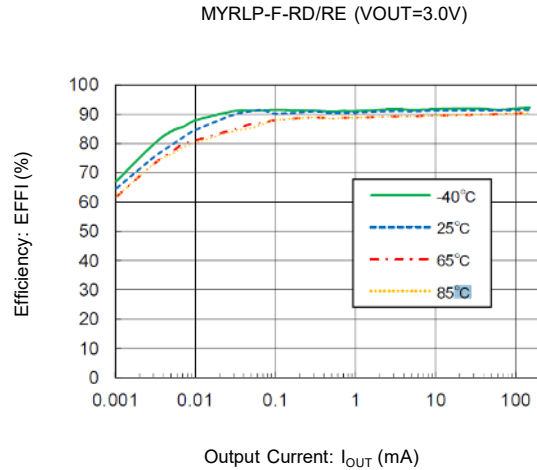
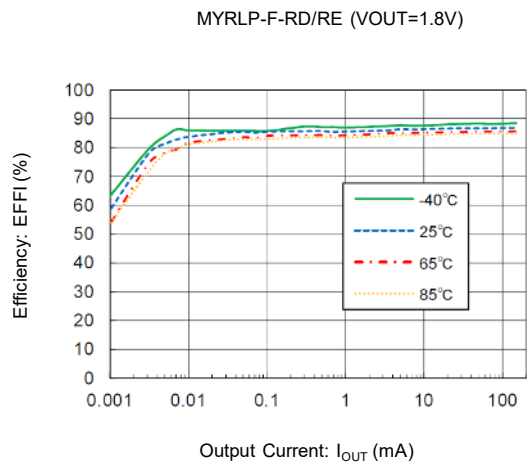
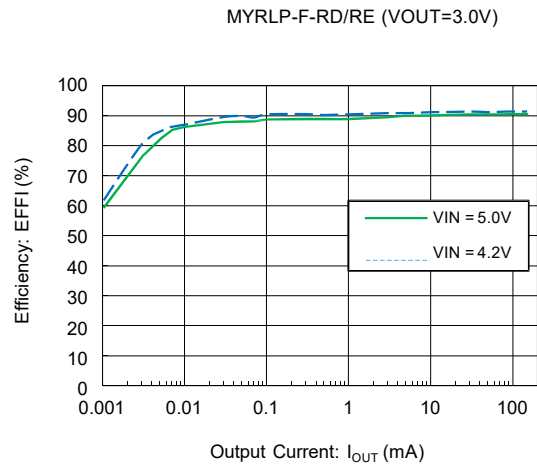
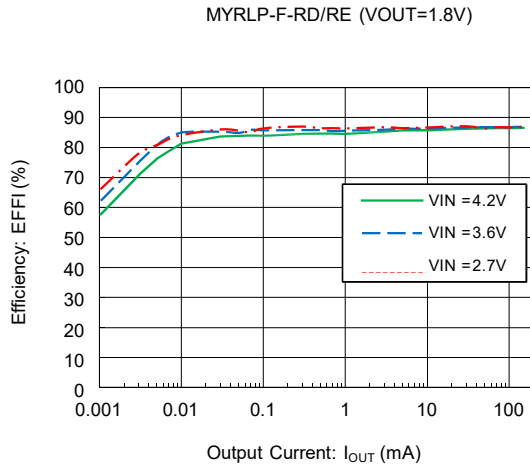
- (1) The coil mounted on this product complies with the general surface mount type chip inductor specifications, and may have scratches, flux stains, etc.
- (2) Do not use this product in the following environments. Places exposed to water or salt water, places where condensation occurs, places where toxic gases (hydrogen sulfide, zinc acid, chlorine, ammonia, etc.) are present.
- (3) Please do not wash this product with solvent.

## ■ Notes on mounting

- (1) Please set the mounting position accuracy within 0.05 mm.

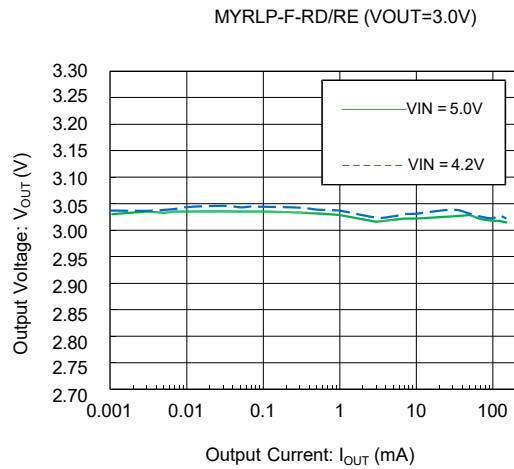
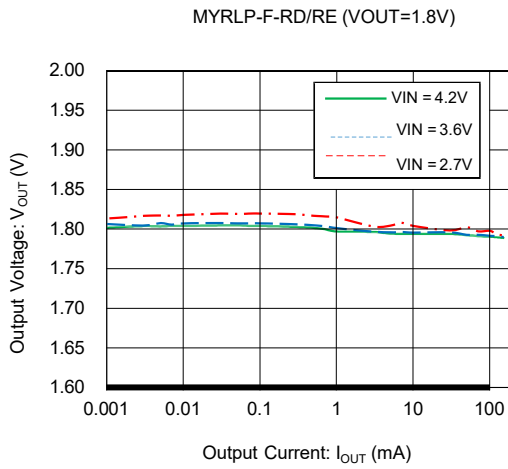
**TYPICAL PERFORMANCE CHARACTERISTICS**

(1) Efficiency vs. Output Current

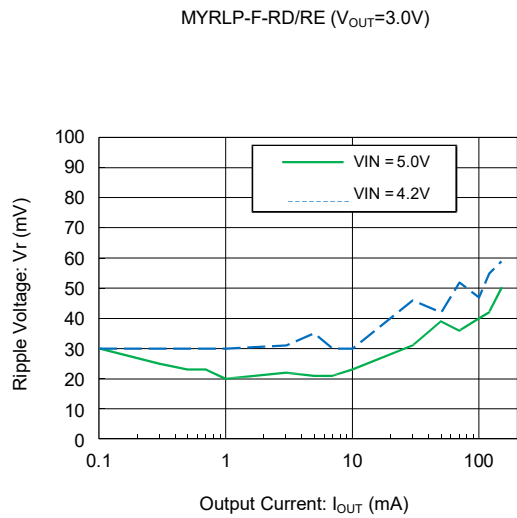
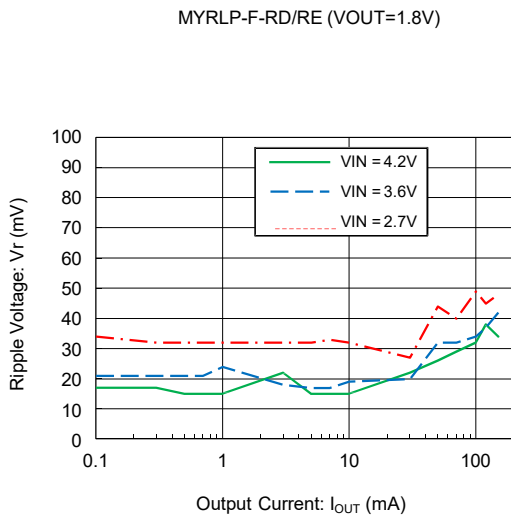


■ **TYPICAL PERFORMANCE CHARACTERISTICS (Continued)**

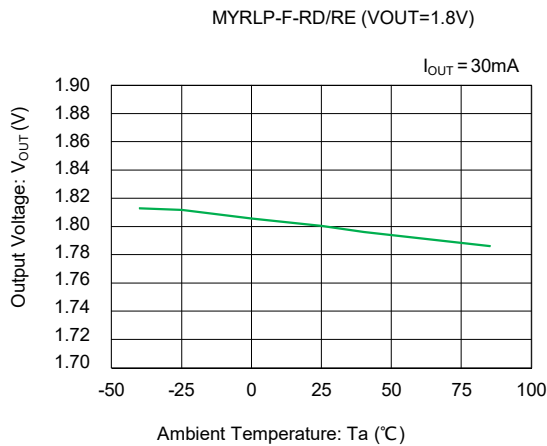
(2) Output Voltage vs. Output Current



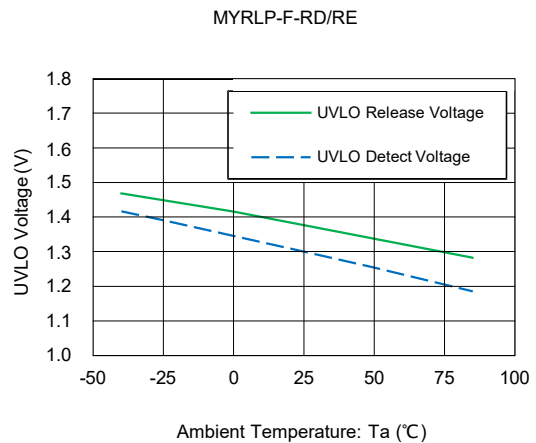
(3) Ripple Voltage vs. Output Current



(4) Output Voltage vs. Ambient Temperature

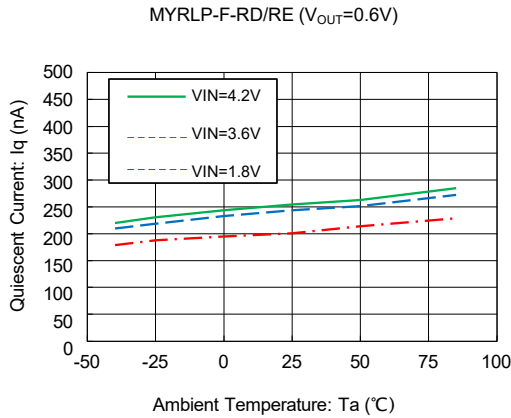


(5) UVLO Voltage vs. Ambient Temperature

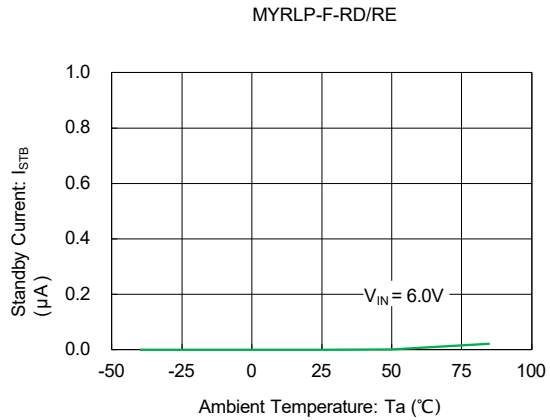


**TYPICAL PERFORMANCE CHARACTERISTICS (Continued)**

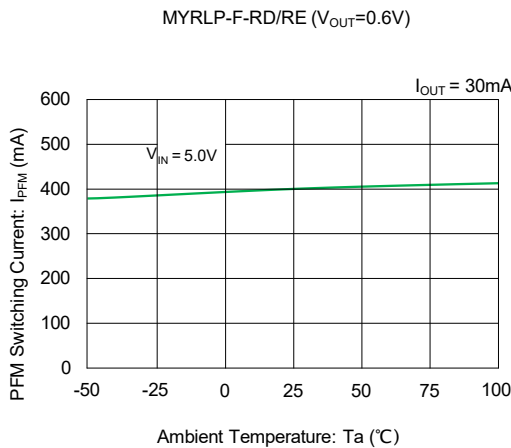
(6) Quiescent Current vs. Ambient Temperature



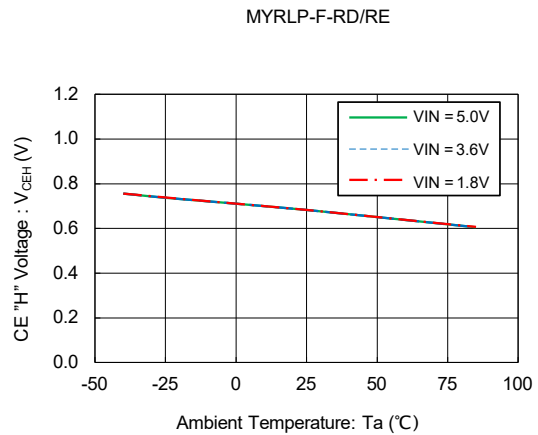
(7) Stand-by Current vs. Ambient Temperature



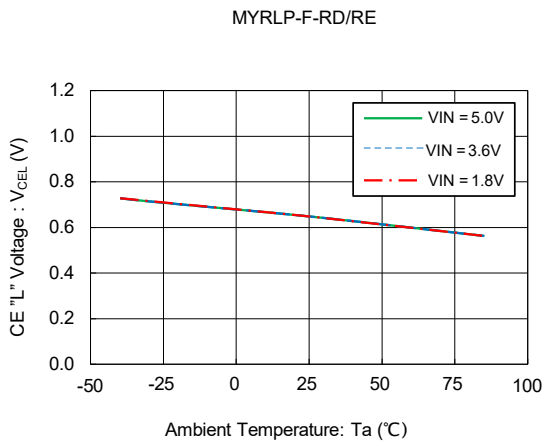
(8) PFM Switching Current vs. Ambient Temperature



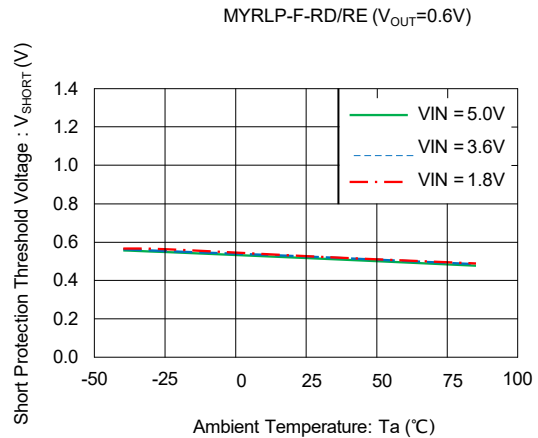
(9) CE "H" Voltage vs. Ambient Temperature



(10) CE "L" Voltage vs. Ambient Temperature



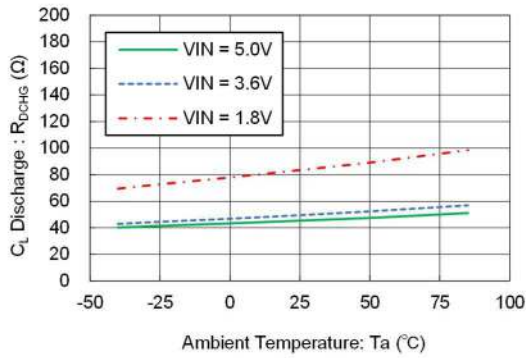
(11) Short Protection Threshold vs. Ambient Temperature



■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(12) CL Discharge Resistance vs. Ambient Temperature

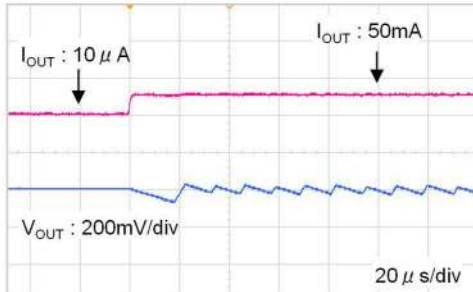
MYRLP-F-RD/RE



(13) Load Transient Responses

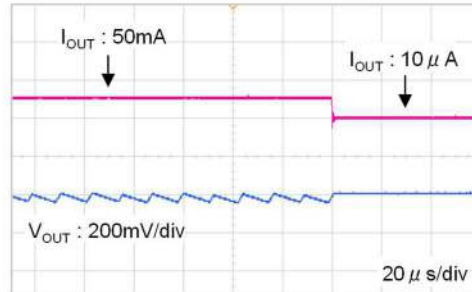
MYRLP-F-RD

$V_{IN} = 3.6V$   $V_{OUT} = 1.8V$   $I_{OUT} = 10\mu A \Rightarrow 50mA$   $tr = 5\mu s$



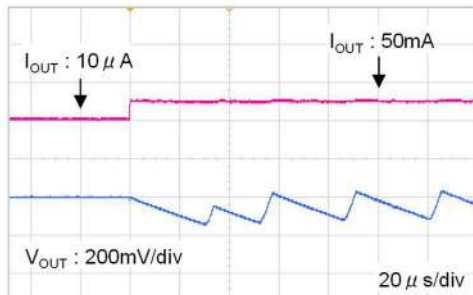
MYRLP-F-RD

$V_{IN} = 3.6V$   $V_{OUT} = 1.8V$   $I_{OUT} = 50mA \Rightarrow 10\mu A$   $tf = 5\mu s$



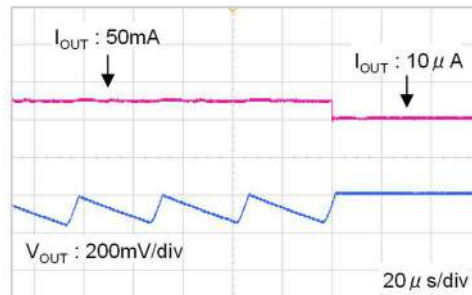
MYRLP-F-RD

$V_{IN} = 3.6V$   $V_{OUT} = 3.0V$   $I_{OUT} = 10\mu A \Rightarrow 50mA$   $tr = 5\mu s$



MYRLP-F-RD

$V_{IN} = 3.6V$   $V_{OUT} = 3.0V$   $I_{OUT} = 50mA \Rightarrow 10\mu A$   $tf = 5\mu s$

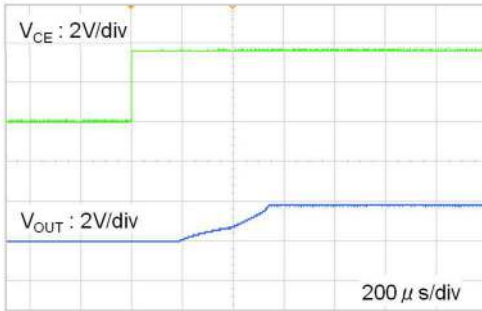


■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

(14) Startup Mode

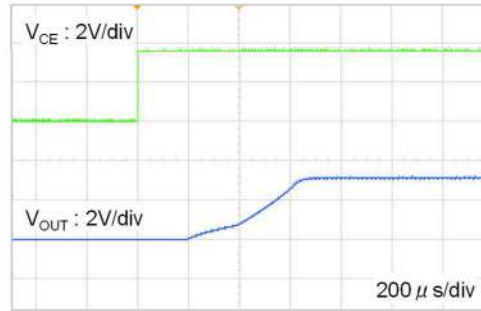
MYRLP-F-RD

$V_{IN} = 3.6V$ ,  $V_{OUT} = 1.8V$ ,  $V_{CE} = 0.0V \Rightarrow 3.6V$ ,  $I_{OUT} = 50mA$   
 $t_r = 5\mu s$



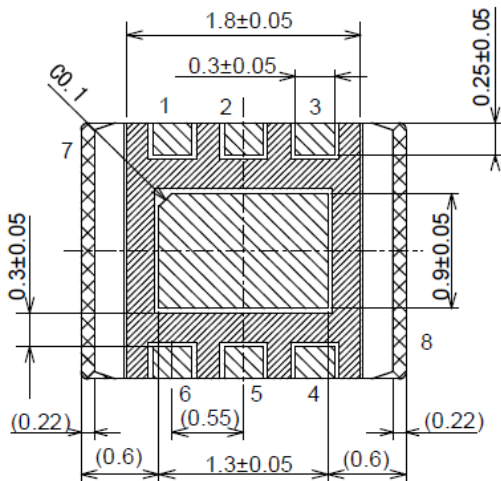
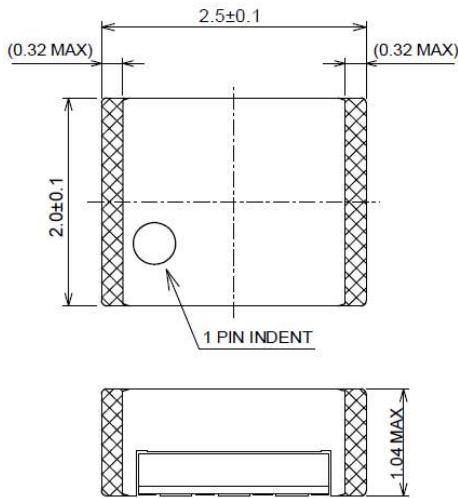
MYRLP-F-RD

$V_{IN} = 3.6V$ ,  $V_{OUT} = 3.0V$ ,  $V_{CE} = 0.0V \Rightarrow 3.6V$ ,  $I_{OUT} = 50mA$   
 $t_r = 5\mu s$



■ **PACKAGING INFORMATION**

● Packaging (2.0mm × 2.5mm, h=1.0mm)



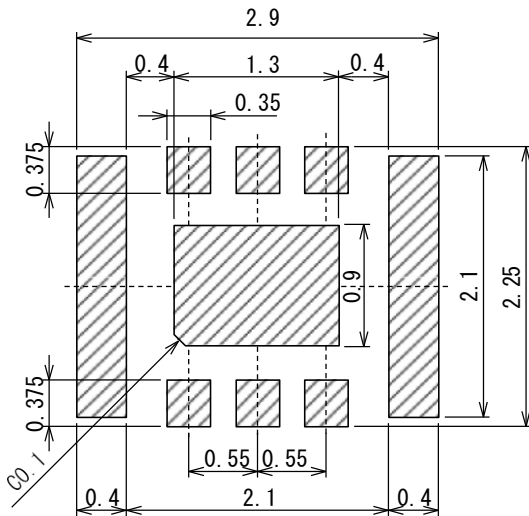
(unit: mm)

Terminal material : Copper foil

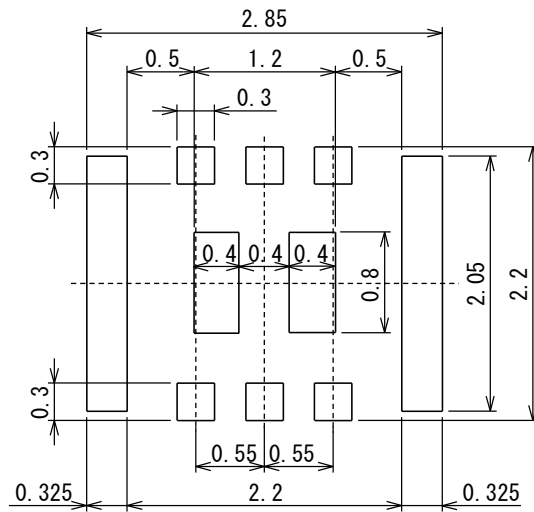
Terminal plating : 1~6 Gold plating

7~8 Lead(Pb) free Solder plating

● Reference Pattern Layout (unit:mm)



● Reference Metal Mask Design (unit:mm)



\*Please use the above mount pad dimensions and metal mask design as reference data.

## ■ PACKAGING INFORMATION

### Power Dissipation

Power dissipation data for the package is shown in this page.  
The value of power dissipation varies with the mount board conditions.  
Please use this data as one of reference data taken in the described condition.

#### 1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

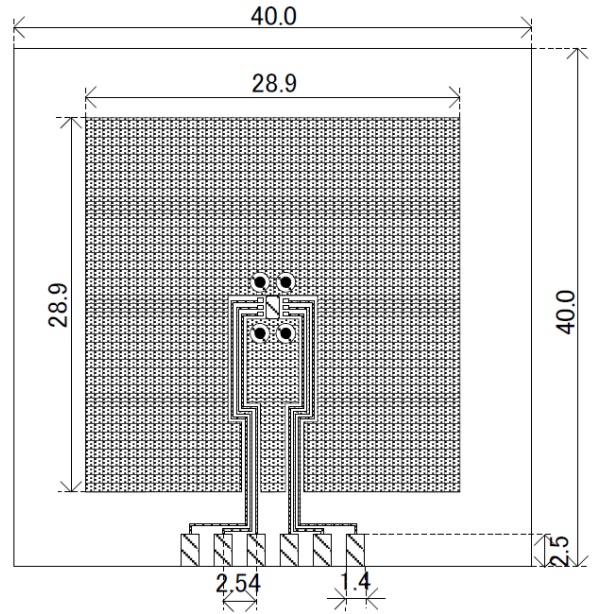
Board Dimensions: 40 x 40 mm (1600mm<sup>2</sup> in one side)  
Copper (Cu) traces occupy 50% of the board area  
In top and back faces Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 4 x 0.8 Diameter

Copper foil thickness: Front 35um, Back 35um

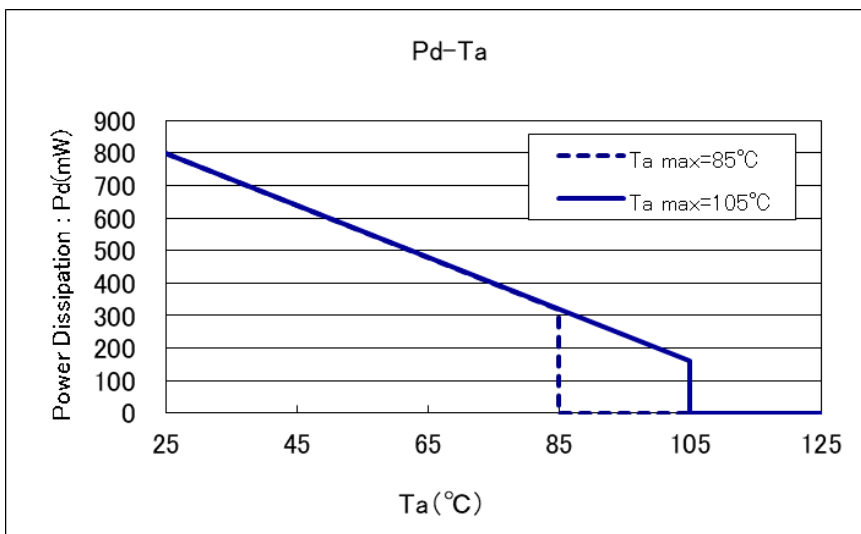


Evaluation Board (Unit:mm)

#### 2. Power Dissipation vs. Ambient Temperature

Board Mount ( T<sub>jmax</sub>=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)		Thermal Resistance (°C/W)
	T <sub>a</sub> max=85°C	T <sub>a</sub> max=105°C	
25	800	800	125.00
85	320	320	
105	0	160	
125	0	0	

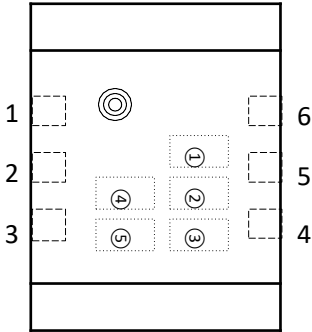




■ MARKING RULE

Mark ① represents product series.

MARK	PRODUCT SERIES
A	MYRLP***015F21RD / MYRLP***015F21RE



Mark ②, ③ represents the registered setting, output voltage.

MARK	Type	OUTPUT VOLTAGE(V)	PRODUCT SERIES
15	E	0.50~3.60V	MYRLP***015F21RE
	D	0.50~3.60V	MYRLP***015F21RD

Mark ④ ⑤ , represents production lot number

01~09, 0A~0Z, 11~9Z, A1~A9, AA~ZZ, B1~ZZ in order.

(G, I, J, O, Q, W excluded) \* No character inversion used.

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